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(57) Abstract :

Embodiments of the present disclosure may include a system (100) to heat and cool liquid, the system including a vessel (102) having an insulated body (110) for storing the liquid to heat and cool. Embodiments may also include a conducting base (106) attached at bottom of the vessel. In some embodiments, the conducting base (106) may include a groove (108). Embodiments may also include a display unit (112) attached to the vessel (102). In some embodiments, the display unit (112) includes a sensor (114) for sensing temperature of the liquid accommodated in the vessel, and the display unit (112) being configured to display the sensed temperature. Embodiments may also include a base plate (118) configured to supply power to the vessel (102), upon receiving the vessel at the base plate (118) and inputs from the user through the display unit (112).

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